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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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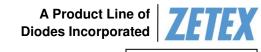












20V PNP HIGH GAIN TRANSISTOR IN SOT223

Features

- BV_{CEO} > -20V
- BV_{ECO} > -4V
- I_C = 8A High Continuous Current
- Low Saturation Voltage V_{CE(sat)} < -47mV @ 1A
- $R_{CE(sat)} = 28m\Omega$
- Complementary PNP Type: ZXTN19020DG
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

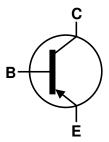
- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound;
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.112 grams (Approximate)

Applications

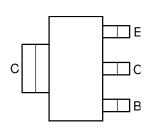
- Motor Drive
- · Relay, Lamp and Solenoid Drive







Device Symbol



Top View Pin-Out

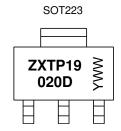
Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP19020DGTA	AEC-Q101	ZXTP19020D	7	12	1,000

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and
- <1000ppm antimony compounds.</p>
 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



ZXTP19020D = Product Type Marking Code YWW = Date Code Marking Y or \overline{Y} = Last Digit of Year (ex: 5= 2015) WW or $\overline{W}W$ = Week Code (01~53)





Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-25	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Collector Voltage (reverse blocking)	V _{ECO}	-4	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	Ic	-8	Α
Base Current	I _B	-1	Α
Peak Pulse Current	I _{CM}	-15	Α

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Note 5)		1.2 9.6		
Power Dissipation	(Note 6)		1.6 12.8	W	
Linear Derating Factor	(Note 7)	P _D	3 24	mW/°C	
	(Note 8)		5.3 42		
	(Note 5)		104		
The word Decistors of Lucation to Austriant	(Note 6)	_	78		
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	42	°C/W	
	(Note 8)		23.5		
Thermal Resistance, Junction to Lead (Note 9)		R _{0JL}	16		
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C		

ESD Ratings (Note 10)

Notes:

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	٧	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

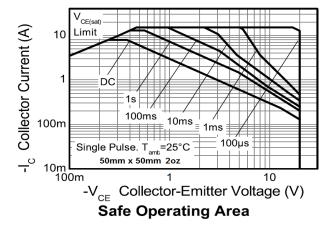
5. For a device mounted with the collector lead on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air

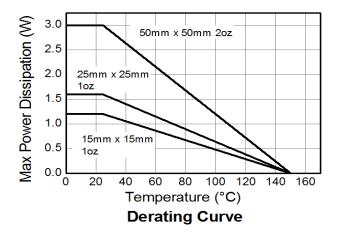
conditions whilst operating in steady-state.

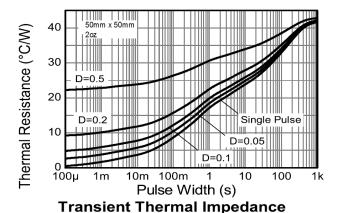
- 6. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.7. Same as Note 6, except the device is mounted on 50mm x 50mm 2oz copper.
- 8. Same as Note 8 measured at t<5 seconds.
- 9. Thermal resistance from junction to solder-point (at the end of the collector lead).
- 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

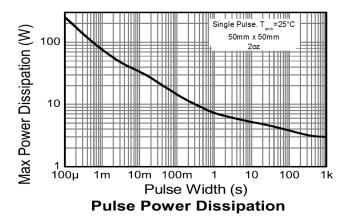


Thermal Characteristics and Derating Information (@T_A = +25°C, unless otherwise specified.)











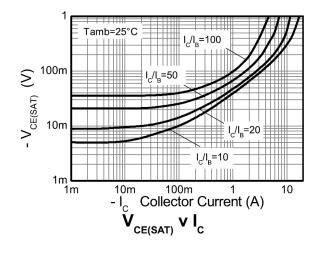
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

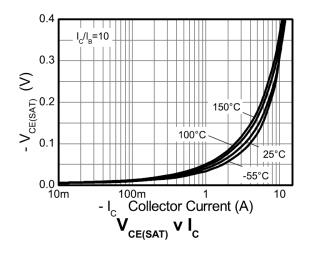
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-25	-55	_	V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 11)	BV _{CEO}	-20	-50	_	V	$I_C = -10mA$
Emitter-Collector Breakdown Voltage (reverse blocking)	BV _{ECX}	-4	-8.6	_	V	$I_C = -100\mu A, R_{BC} < 1k\Omega or$ 0.25V < $V_{BC} > -0.25V$
Emitter-Collector Breakdown Voltage (reverse blocking)	BV _{ECO}	-4	-8.6	_	V	I _E = -100μA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.2	_	V	I _E = -100μA
Collector Cut-Off Current	1	_	< 1	-50	nA	V _{CB} = -25V
Collector Gut-Oil Gullent	I _{CBO}	-	_	-0.5	μΑ	$V_{CB} = -25V, T_A = +100^{\circ}C$
Emitter Cut-Off Current	I _{EBO}	=	< 1	-50	nA	$V_{EB} = -5.6V$
	V _{CE(sat)}	_	-40	-47	mV	$I_C = -1A$, $I_B = -100mA$
Collector-Emitter Saturation Voltage (Note 11)		_	-97	-130	mV	$I_C = -1A$, $I_B = -10mA$
Collector-Emitter Saturation Voltage (Note 11)		=	-115	-145	mV	$I_C = -2A$, $I_B = -40mA$
		-	-220	-275	mV	$I_C = -8A$, $I_B = -800mA$
Base-Emitter Saturation Voltage (Note 11)	$V_{BE(sat)}$	-	-1050	-1150	mV	$I_C = -8A$, $I_B = -800mA$
Base-Emitter Turn-On Voltage (Note 11)	$V_{BE(on)}$	-	-930	-1000	mV	$I_{C} = -8A$, $V_{CE} = -2V$
	h _{FE}	300	450	900	I	$I_C = -100 \text{mA}, V_{CE} = -2 \text{V}$
DC Current Gain (Note 11)		200	290	_	I	$I_{C} = -2A$, $V_{CE} = -2V$
Do Guiterit Gairi (Note 11)		45	70	_	-	$I_{C} = -8A, V_{CE} = -2V$
		=	25	_	-	$I_C = -15A$, $V_{CE} = -2V$
Current Gain-Bandwidth Product (Note 11)	f⊤	-	176	-	MHz	$V_{CE} = -10V, I_{C} = -50mA,$ f = 50MHz
Input Capacitance (Note 11)	C _{ibo}	_	_	400	рF	$V_{EB} = -0.5V, f = 1MHz$
Output Capacitance (Note 11)	C_{obo}	_	36	45	рF	V _{CB} = -10V, f = 1MHz
Delay Time	t _d	-	23		ns	
Rise Time	t _r	_	18.4	_	ns	$I_C = -1A$, $V_{CC} = -10V$,
Storage Time	t _s	_	266	_	ns	$I_{B1} = -I_{B2} = -50 \text{mA}$
Fall Time	t _f	_	49.6	_	ns]

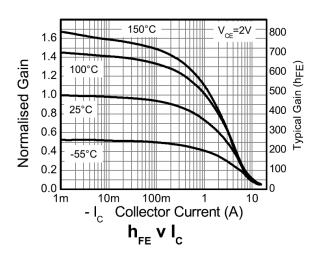
Note: 11. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.

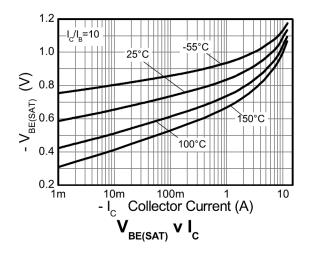


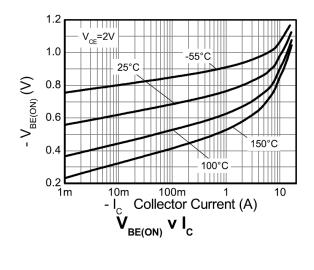
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

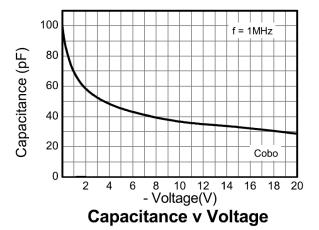








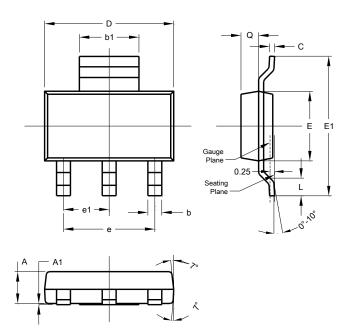






Package Outline Dimensions

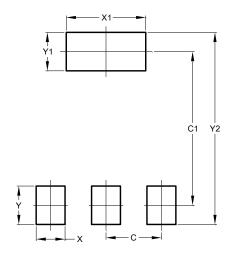
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.30
C1	6.40
X	1.20
X1	3.30
Υ	1.60
Y1	1.60
Y2	8.00





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